

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A lead frame for an integrated circuit package comprising: a substantially radiation transparent composite lead frame of a plastic material having a portion thereof including an intrinsic conductive polymer.

2. (Previously Presented) The lead frame of claim 1, further comprising: an adhesive located on a portion of the composite lead frame.

3. (Previously Presented) The lead frame of claim 1, wherein the intrinsic conductive polymer is a polyaniline.

4. (Previously Presented) The lead frame of claim 1, wherein the composite lead frame is transparent.

5. (Currently Amended) A circuit card comprising:
at least one electronic device;
a circuit card; and
at least one connector for attaching a portion of the at least one electronic device to a portion of the circuit card, the at least one electronic device comprising an integrated circuit die attached to a portion of a substantially radiation transparent plastic lead frame, the substantially radiation transparent plastic lead frame including an intrinsic conductive polymer.

6. (Previously Presented) The circuit card of claim 5, wherein the plastic lead frame further comprises a plastic lead frame structure coated with a conductive polymer.

7. (Previously Presented) The circuit card of claim 6, wherein the conductive polymer coating is selected from the group consisting of polyaniline.
8. (Previously Presented) The circuit card of claim 7, wherein the polyaniline coating is of a thickness between about 25 μm and about 75 μm .
9. (Previously Presented) The circuit card of claim 5, wherein the plastic lead frame is composite plastic formed of a conventional polymer intermixed with a conductive polymer.
10. (Previously Presented) A computer system comprising at least one circuit card, the at least one circuit card comprised of a plurality of electronic devices, at least one electronic device of the plurality comprising at least one integrated circuit die connected to a portion of a plastic lead frame including an intrinsic polymer material.
11. (Previously Presented) The computer system of claim 10, wherein the plastic lead frame further comprises a plastic lead frame structure coated with a conductive polymeric coating.
12. (Previously Presented) The computer system of claim 11, wherein the conductive polymeric coating is selected from the group consisting of polyaniline.
13. (Previously Presented) The computer system of claim 10, wherein the plastic lead frame is composite plastic formed of a conventional polymer intermixed with a conductive polymer.
14. (Currently Amended) An encapsulated semiconductor assembly including portions of a lead frame extending therefrom and an integrated circuit die comprising:
a lead frame of a plastic material that is conductive;
an integrated circuit die having a plurality of bond pads on a surface thereof; and

at least one connection between a portion of the lead frame and at least one bond pad of the integrated circuit die.

15. (Previously Presented) The assembly of claim 14, further comprising:
an adhesive located on a portion of the lead frame.

16. (Previously Presented) The assembly of claim 1, wherein the intrinsic conductive polymer comprises a polyaniline.

17. (Previously Presented) The assembly of claim 14, wherein the lead frame comprises a transparent lead frame.

18. (Previously Presented) The assembly of claim 14, wherein the at least one connection comprises a bond wire.

19. (Previously Presented) The assembly of claim 14, wherein the at least one connection comprises a conductive epoxy.

20. (Previously Presented) The assembly of claim 14, wherein the at least one connection comprises a Z-axis conductive material.

21. (Previously Presented) The assembly of claim 14, wherein the at least one connection comprises a direct connection.